

# 600V, 40A, Trench FS II Fast IGBT

## General Description:

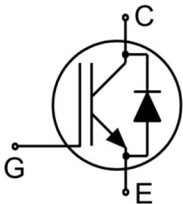
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

### Features

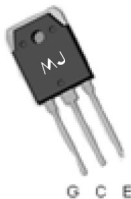
- ◆ Trench FSII Technology offering
- ◆ Very low  $V_{CE(sat)}$
- ◆ High speed switching
- ◆ Positive temperature coefficient in  $V_{CE(sat)}$
- ◆ Very tight parameter distribution
- ◆ High ruggedness, temperature stable behavior

### Application

- ◆ Air Condition
- ◆ Inverters
- ◆ Motor drives



Schematic diagram



TO-3P

## Package Marking and Ordering Information

Device	Device Package	Device Marking
MJ40TD60BP	TO-3P	MJ40TD60BP

## Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	$V_{CES}$	600	V
Gate- Emitter Voltage	$V_{GES}$	±30	V
Collector Current	$I_C$	80	A
Collector Current @Tc = 100 °C	$I_C$	40	A
Pulsed Collector Current, tp limited by Tjmax	$I_{Cplus}$	120	A
turn off safe operating area, VCE=600V, Tj=150°C	-	120	A
Diode Continuous Forward Current @Tc = 100 °C	$I_F$	40	A
Diode Maximum Forward Current	$I_{FM}$	120	A
Power Dissipation @ Tc = 25°C	$P_D$	286	W
Power Dissipation @Tc = 100 °C	$P_D$	143	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +175	°C
Maximum Temperature for Soldering	$T_L$	260	°C
Short circuit withstand time VGE=15.0V, VCC≤400V, Allowed number of short circuits<1000Time between short circuits:≥1.0s, Tj≤150°C	$t_{sc}$	5	us

Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	0.52	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	2.12	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	40	$^{\circ}\text{C/W}$

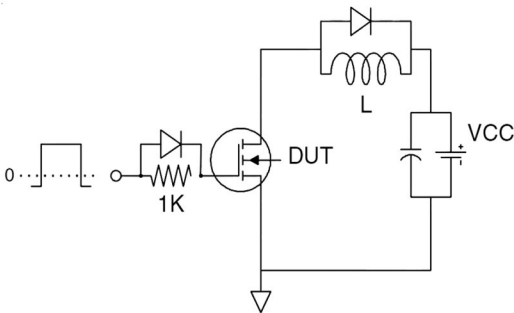
Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			Units
				Min	Typ	Max	
Static Characteristics							
Collector-Emitter Breakdown Voltage	V <sub>(BR)CES</sub>	V <sub>GE</sub> =0V,I <sub>CE</sub> =1mA		600	-	-	V
Collector-Emitter Leakage Current	I <sub>CES</sub>	V <sub>GE</sub> =0V,V <sub>CE</sub> =600V		-	-	4	μA
Gate to Emitter Forward Leakage	I <sub>GES(F)</sub>	V <sub>GE</sub> =+30V,V <sub>CE</sub> =0V		-	-	200	nA
Gate to Source Reverse Leakage	I <sub>GES(R)</sub>	V <sub>GE</sub> =-30V,V <sub>CE</sub> =0V		-	-	200	nA
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =40A V <sub>GE</sub> =15V	T <sub>J</sub> =25°C	-	1.7	1.9	V
			T <sub>J</sub> =150°C	-	1.9	-	V
Gate Threshold Voltage	V <sub>GE(th)</sub>	I <sub>C</sub> =1mA, V <sub>CE</sub> =V <sub>GE</sub>		4.0	5.0	6.0	V
Dynamic Characteristics							
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> =25V,V <sub>GE</sub> =0V, f=1MHz		-	4894	-	pF
Output Capacitance	C <sub>Oss</sub>			-	136	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	94	-	pF
Total Gate Charge	Q <sub>g</sub>	V <sub>CC</sub> =480V, I <sub>C</sub> =40A V <sub>GE</sub> =15V		-	176	-	nC
Gate to Emitter Charge	Q <sub>ge</sub>			-	38	-	nC
Gate to Collector Charge	Q <sub>gc</sub>			-	73	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	I <sub>C(SC)</sub>	V <sub>GE</sub> =15V,V <sub>CC</sub> ≤400V, t <sub>sc</sub> ≤5us,T <sub>J</sub> ≤150°C		-	250	-	A
Switching Characteristics							
Turn-on Delay Time	t <sub>d(ON)</sub>	V <sub>CE</sub> =400V,I <sub>C</sub> =40A V <sub>GE</sub> =0/15V, R <sub>g</sub> =5Ω Inductive Load		-	19	-	ns
Rise Time	t <sub>r</sub>			-	17	-	ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>			-	168	-	ns
Fall Time	t <sub>f</sub>			-	16	-	ns
Turn-On Switching Loss	E <sub>on</sub>			-	0.58	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>			-	0.48	-	mJ
Turn-Off Switching Loss	E <sub>ts</sub>			-	1.06	-	mJ

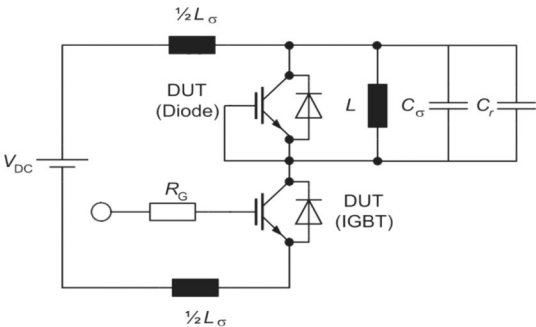
### Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Parameter	Symbol	Test Conditions	Rating			Units
			Min	Typ	Max	
Diode Forward Voltage	V <sub>FM</sub>	I <sub>F</sub> =40A	-	1.65	2.0	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =40A,di/dt=200A/uS	-	242	-	ns
Diode Peak Reverse Recovery Current	I <sub>RRM</sub>		-	3.9	-	A
Reverse Transfer Capacitance	Q <sub>rr</sub>		-	0.44	-	uC
Pulse width ttp≤380μs,δ≤2%						

### Test Circuit

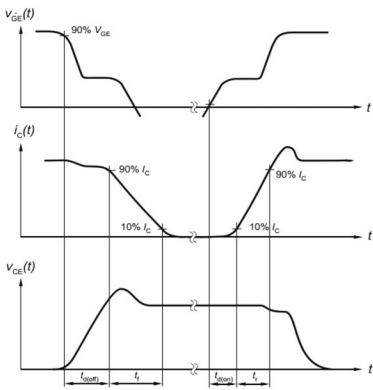


Gate Charge Test Circuit

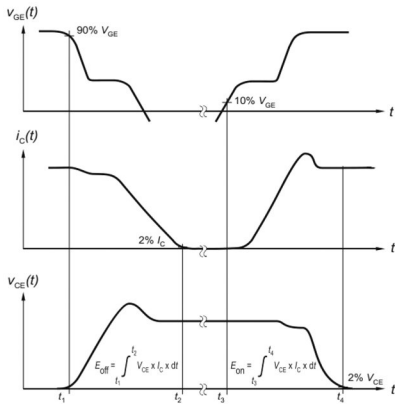


Switch Time Test Circuit

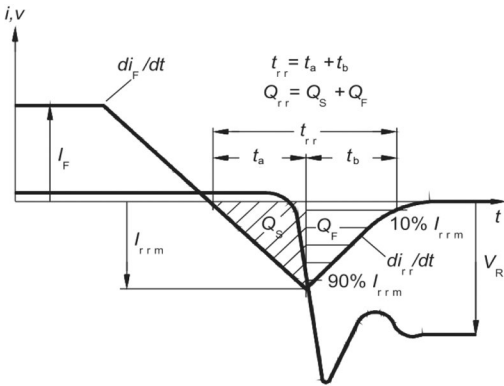
### Switching characteristics



definition of switching times



definition of switching losses



Definition of diode switching characteristics

Typical Electrical and Thermal Characteristics

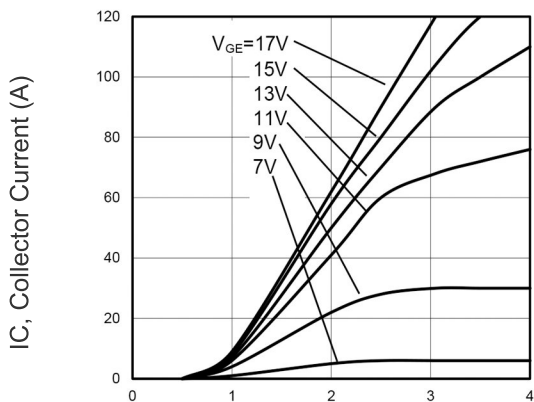


Figure 1 Output Characteristics

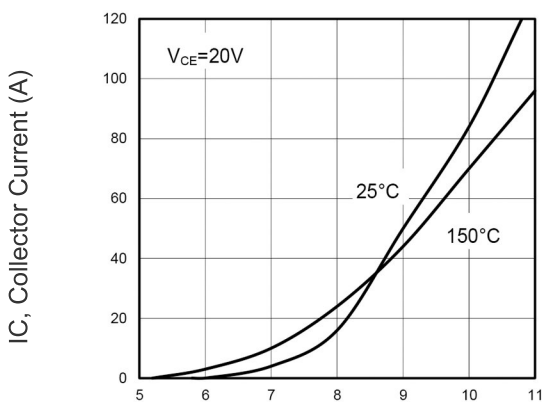


Figure 2 Transfer Characteristics

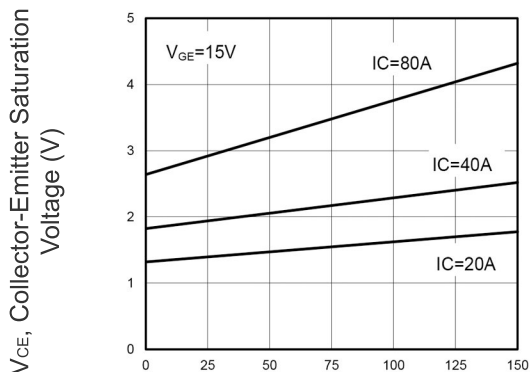


Figure 3  $V_{CEsat}$  vs. Case Temperature

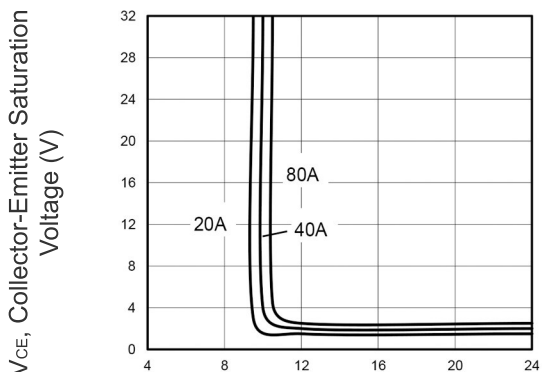


Figure 4 Saturation Voltage vs.  $V_{GE}$

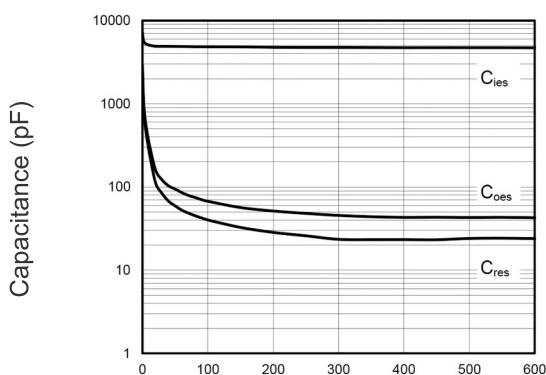


Figure 5 Capacitance Characteristics

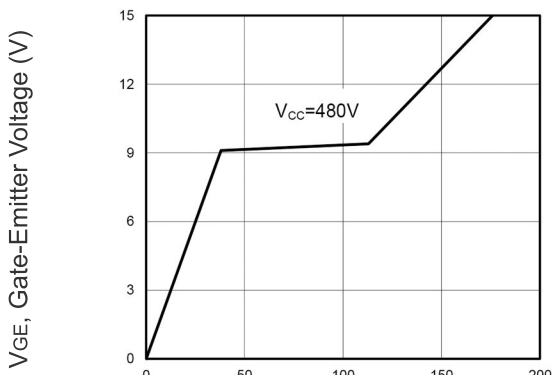
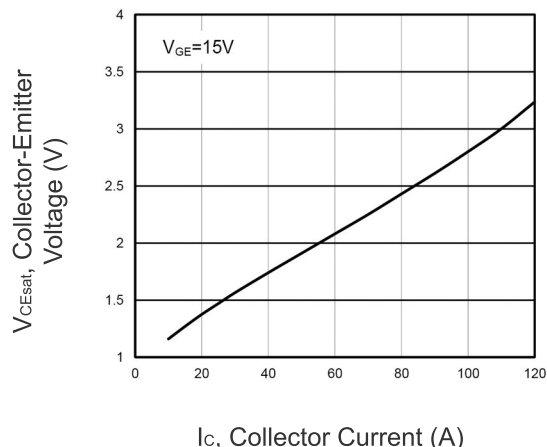
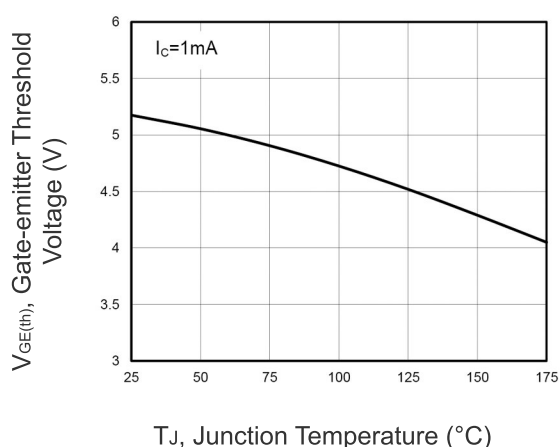
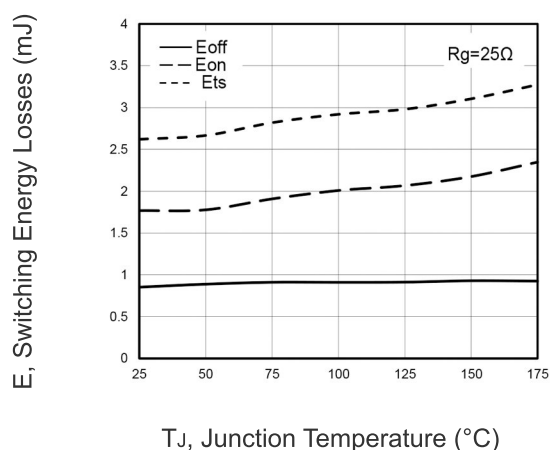
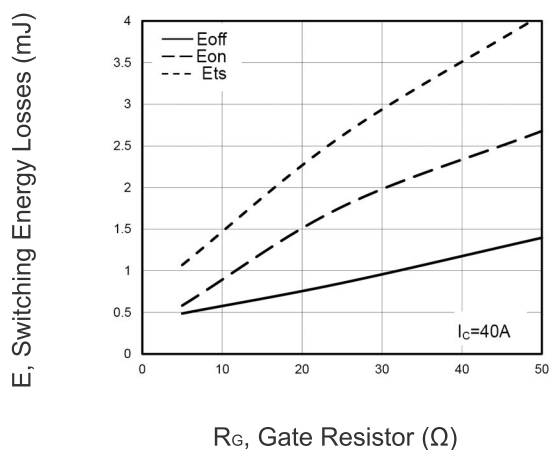
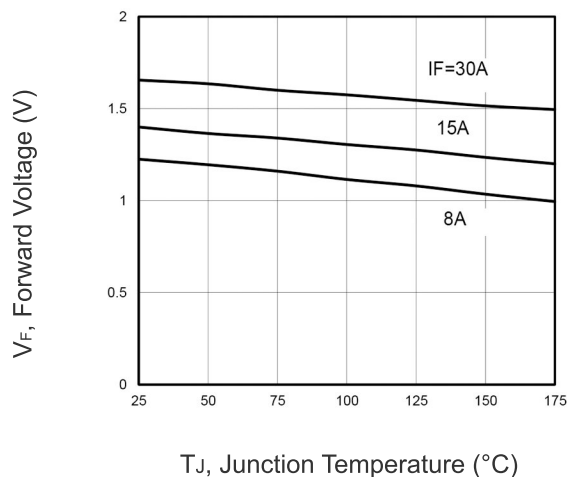
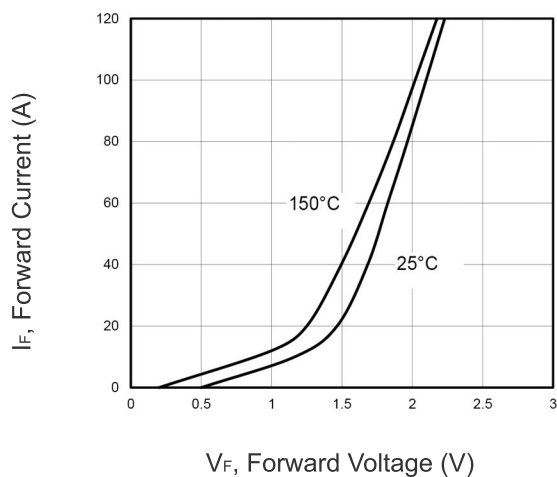


Figure 6 Gate charge waveform

## Typical Electrical and Thermal Characteristics



## Typical Electrical and Thermal Characteristics

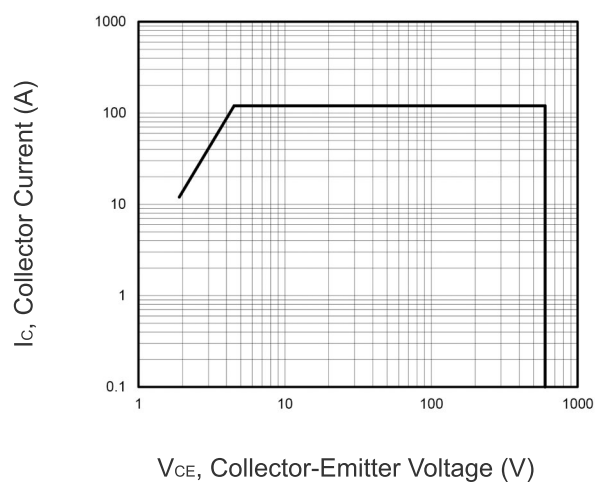
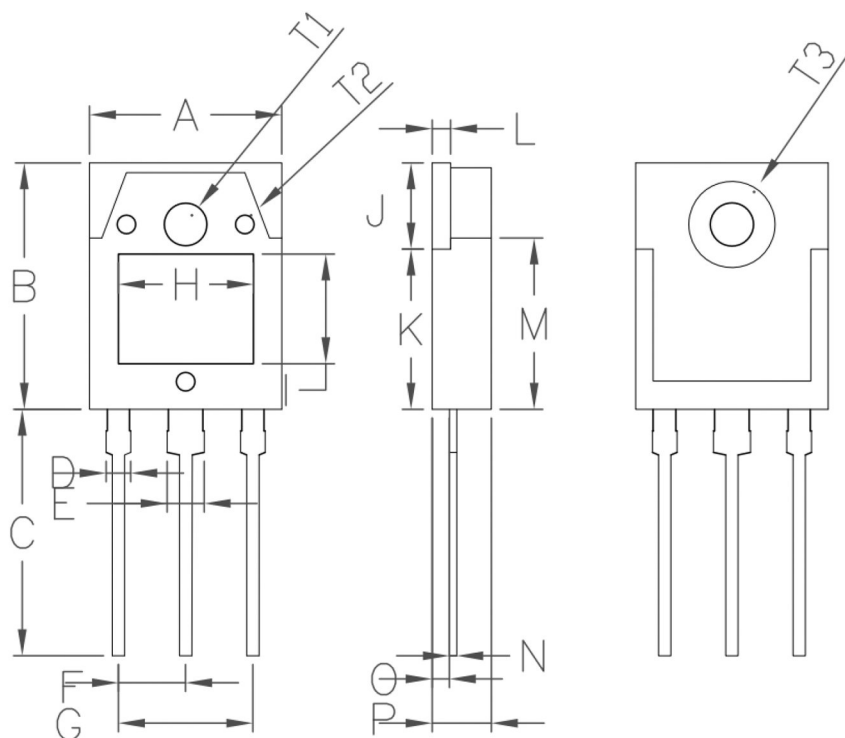


Figure 13 Forward Bias Safe Operating Area

# TO-3P-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	15.50	15.70	0.61	0.62
B	19.70	20.10	0.78	0.79
C	20.10	20.50	0.79	0.81
D	2.00		0.08	
E	3.00		0.12	
F	5.45		0.21	
G	10.90		0.43	
H	10.80	11.00	0.43	0.43
I	8.80	9.00	0.35	0.35
J	6.85	7.15	0.27	0.28
K	12.75	13.05	0.50	0.51
L	1.49	1.51	0.06	0.06
M	13.70	14.00	0.54	0.55
N	0.59	0.61	0.02	0.02
O	1.32	1.48	0.05	0.06
P	4.70	4.90	0.19	0.19
S	4°		0.16°	
T1	3.50		0.14	
T2	1.50		0.06	
T3	7.00		0.28	

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